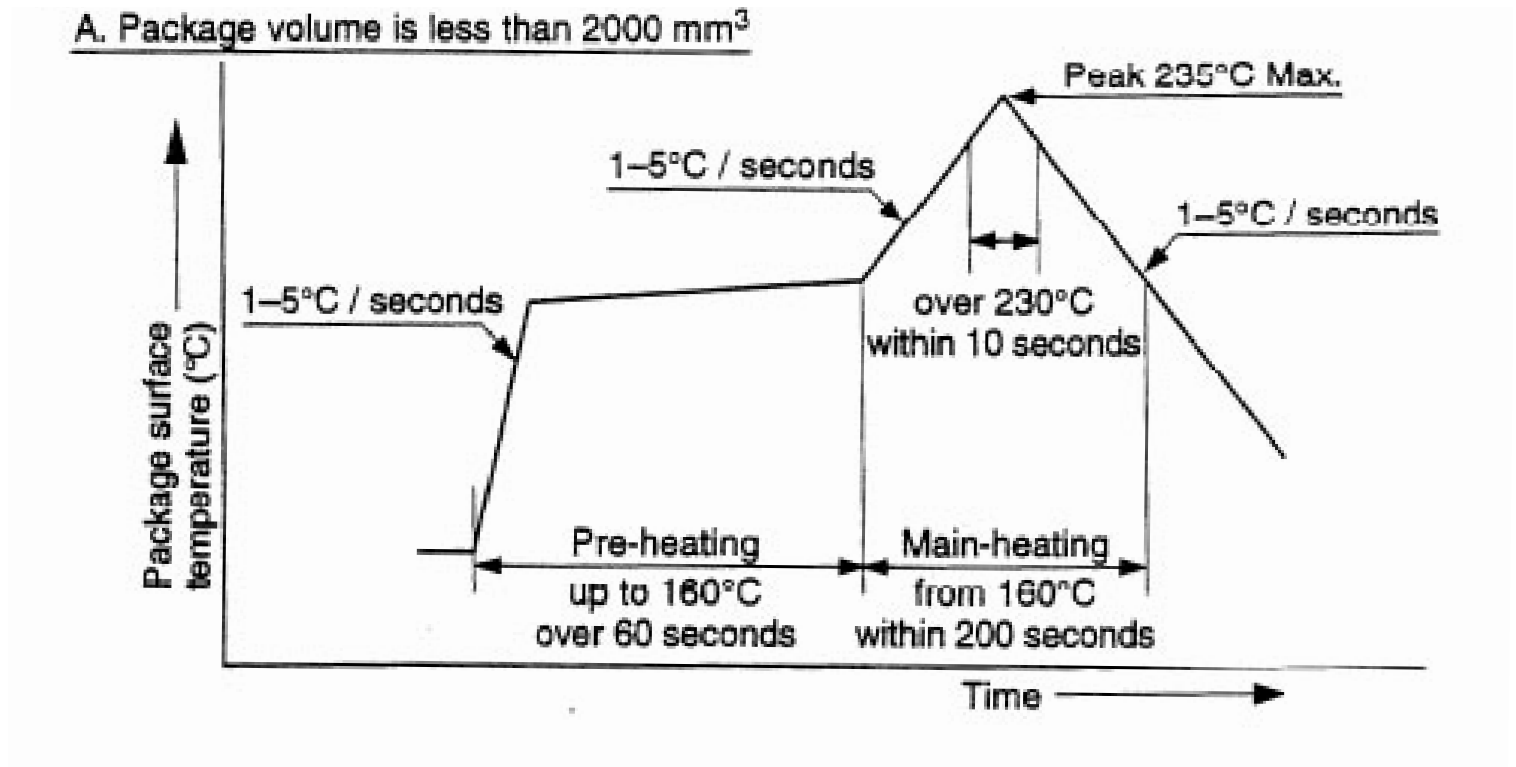


Temperature Profile for PQFP Packages

This process combines air reflow and infrared reflow. The resin surface temperature at maximum should be 235°C for not longer than 10 seconds. It is preferred that the time and temperature are shorter.



PLX Technology, Inc.
870 Maude Ave.
Sunnyvale, CA 94085 USA

Tel: 408 774 9060
Fax: 408 774 2169
Email: info@plxtech.com